

ABSTRACT

A connector is provided for reducing the effects of differential coefficient of thermal expansion of the connector and the underlying circuit board. The connector exhibits high coplanarity along the mounting interface by providing an insulative connector housing in which stress buildup is avoided. The connector housing incorporates compliant sections corresponding to the areas where the greatest deformation in the substrate is expected. The housing has notches or slots at locations furthest from the neutral point (NP) of the connector (i.e., around the corners). By means of this arrangement, stress buildup is avoided, so as to minimize warping and twisting of the housing.